



## Material Content Data Sheet



<b>Sales Product Name</b>		TLV4968-1TA		<b>Issued</b>		23. January 2018			
<b>MA#</b>		MA001282252							
<b>Package</b>		PG-TO92S-3-1		<b>Weight*</b>		126.87 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.350	0.28	0.28	2755	2755	
leadframe	non noble metal	iron	7439-89-6	0.091	0.07		717		
	inorganic material	phosphorus	7723-14-0	0.027	0.02		215		
	non noble metal	copper	7440-50-8	90.909	71.66	71.75	716527	717459	
wire	noble metal	gold	7440-57-5	0.029	0.02	0.02	229	229	
encapsulation	organic material	carbon black	1333-86-4	0.089	0.07		701		
	plastics	epoxy resin	-	2.727	2.15		21492		
	inorganic material	silicondioxide	60676-86-0	26.823	21.14	23.36	211416	233609	
leadfinish	non noble metal	tin	7440-31-5	5.498	4.33	4.33	43334	43334	
plating	noble metal	silver	7440-22-4	0.153	0.12	0.12	1206	1206	
glue	plastics	epoxy resin	-	0.036	0.03		282		
	noble metal	silver	7440-22-4	0.143	0.11	0.14	1126	1408	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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